IN THE CLAIMS

Claims 2-3 are pending in this application. Please cancel claim 1 without prejudice or disclaimer, and amend claims 2-3 as follows:

- 1. (Canceled)
- 2. (Currently Amended) A method for purifying semiconductor nanoparticles, comprising the steps of:

modifying semiconductor nanoparticles with oil-soluble materials for surface modification;

converting the oil-soluble materials for surface modification into water-soluble materials for surface modification at the interface between an organic solvent and water;

shifting the semiconductor nanoparticles from an organic phase to an aqueous phase by the conversion; and then

subjecting the semiconductor nanoparticles, the surfaces of which have been modified with the water-soluble materials for surface modification, to size-selective photoetching, wherein the surface of the semiconductor nanoparticles is dissolved and peeled by the size-selective photoetching, and particle sizes of the semiconductor nanoparticles are regulated and the semiconductor nanoparticles are monodispersed by the dissolution, thereby regulating particle sizes of the semiconductor nanoparticles and monodispersing the semiconductor nanoparticles.

3. (Currently Amended) A method for purifying semiconductor nanoparticles, comprising the steps of:

modifying semiconductor nanoparticles with oil-soluble materials for surface modification;

converting the oil-soluble materials for surface modification into water-soluble materials for surface modification at the interface between an organic solvent and water;

shifting the semiconductor nanoparticles from an organic phase to an aqueous phase by the conversion; and then

subjecting the semiconductor nanoparticles, the surfaces of which have been modified with the water-soluble materials for surface modification, to size-selective photoetching, wherein the surface of the semiconductor nanoparticles is dissolved and peeled by the size-selective photoetching, and the materials for surface modification is converted by the dissolution whereby the dissolution caused thereby is utilized to peel the surfaces of the semiconductor nanoparticles, thereby converting the materials for surface modification.